

NEC**PHOTOCOUPLER**
PS2506-1,-2,-4,PS2506L-1,-2,-4**HIGH ISOLATION VOLTAGE**
AC INPUT, DARLINGTON TRANSISTOR TYPE
MULTI PHOTOCOUPLER SERIES

-NEPOC Series-

DESCRIPTION

The PS2506-1, -2, -4 and PS2506L-1, -2, -4 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon darlington connected phototransistor.

The PS2506-1, -2, -4 are in a plastic DIP (Dual In-line Package) and the PS2506L-1, -2, -4 are lead bending type (Gull-wing) for surface mount.

FEATURES

- AC input response
- High isolation voltage ($BV = 5\,000\text{ Vr.m.s.}$)
- High current transfer ratio ($CTR = 2\,000\% \text{ TYP.}$)
- High-speed switching ($t_r, t_f = 100\ \mu\text{s TYP.}$)
- Ordering number of tape product: PS2506L-1-E3, E4, F3, F4, PS2506L-2-E3, E4
- Safety standards
 - UL approved: File No. E72422

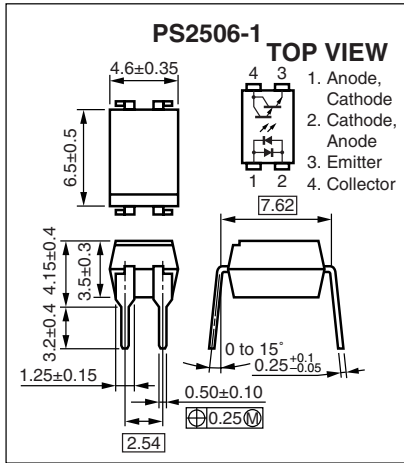
APPLICATIONS

- Power supply
- Telephone/FAX
- FA/OA equipment
- Programmable logic controller

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.
Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

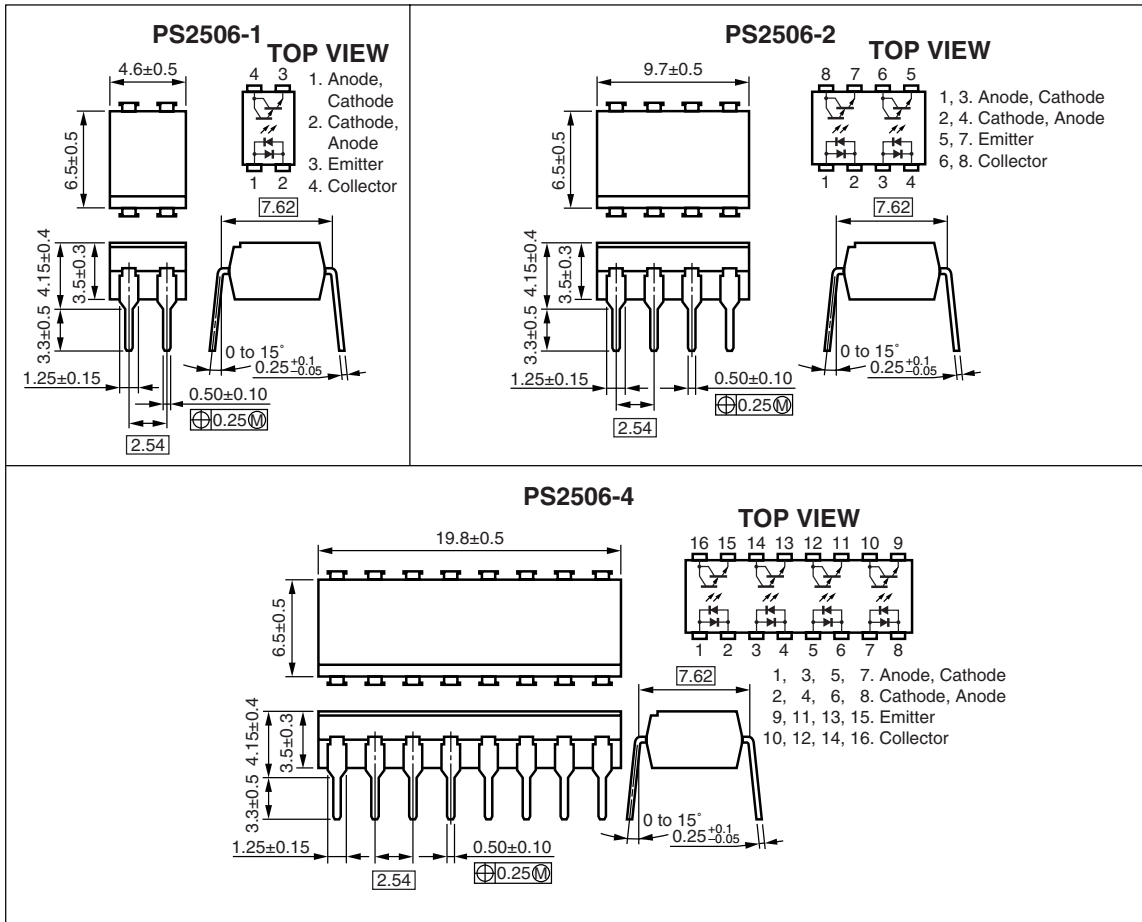
PACKAGE DIMENSIONS (UNIT : mm)

DIP Type (New package)

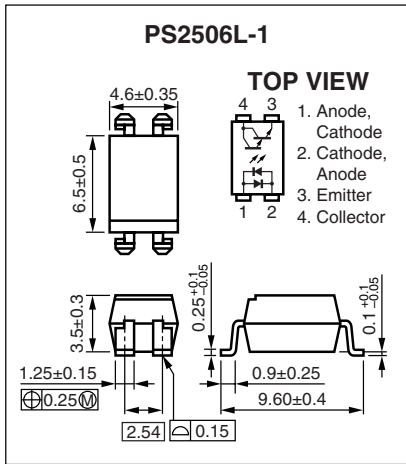


Caution New package 1-ch only

DIP Type

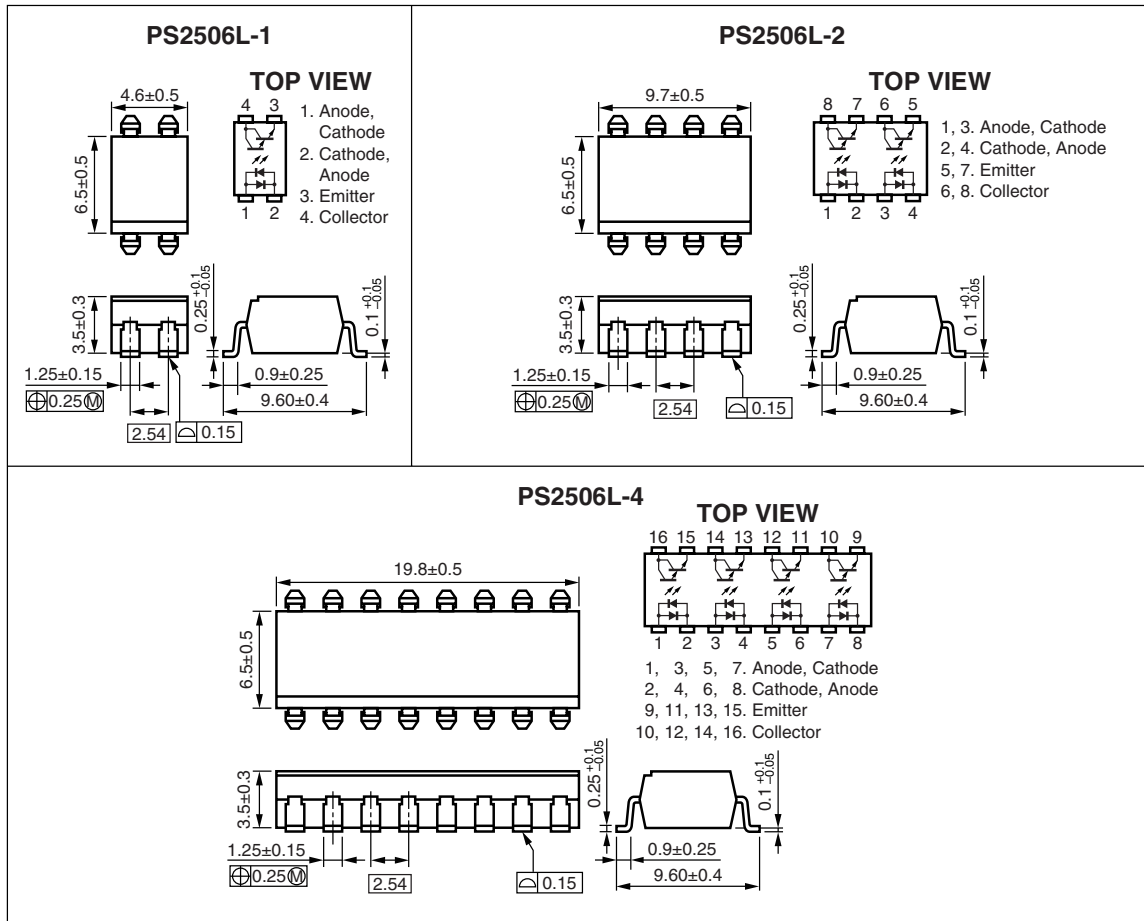


Lead Bending Type (New package)

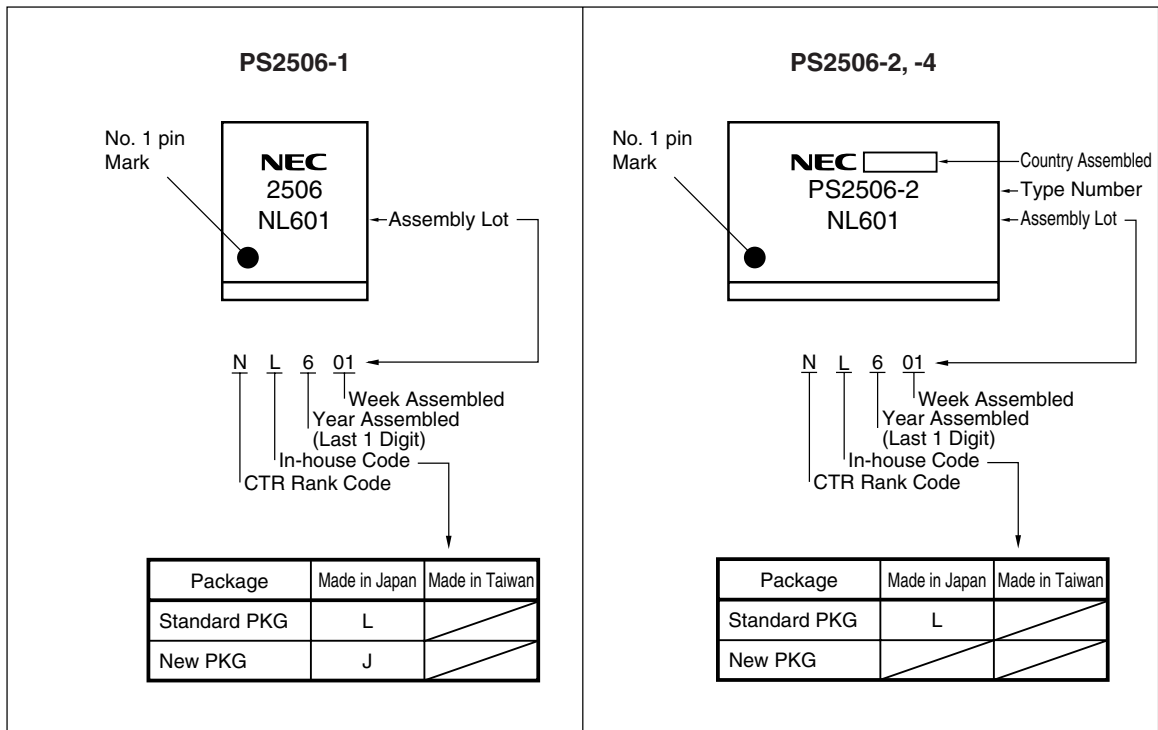


Caution New package 1-ch only

Lead Bending Type



★ MARKING EXAMPLE



★ ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ¹
PS2506-1	PS2506-1-A	Pb-Free	Magazine case 100 pcs	Standard products (UL Approved)	PS2506-1
PS2506L-1	PS2506L-1-A		Embossed Tape 1 000 pcs/reel		
PS2506L-1-E3	PS2506L-1-E3-A				
PS2506L-1-E4	PS2506L-1-E4-A				
PS2506L-1-F3	PS2506L-1-F3-A				
PS2506L-1-F4	PS2506L-1-F4-A				
PS2506-2	PS2506-2-A				Magazine case 45 pcs
PS2506L-2	PS2506L-2-A		Embossed Tape 1 000 pcs/reel		
PS2506L-2-E3	PS2506L-2-E3-A				
PS2506L-2-E4	PS2506L-2-E4-A				
PS2506-4	PS2506-4-A				Magazine case 20 pcs
PS2506L-4	PS2506L-4-A				

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS2506-1, PS2506L-1	PS2506-2,-4 PS2506L-2,-4	
Diode	Forward Current (DC)	I _F	±80		mA/ch
	Power Dissipation Derating	ΔP _D /°C	1.5	1.2	mW/°C
	Power Dissipation	P _D	150	120	mW/ch
	Peak Forward Current ¹	I _{FP}	±1		A/ch
Transistor	Collector to Emitter Voltage	V _{CEO}	40		V
	Emitter to Collector Voltage	V _{ECO}	6		V
	Collector Current	I _C	200	160	mA/ch
	Power Dissipation Derating	ΔP _C /°C	2.0	1.6	mW/°C
	Power Dissipation	P _C	200	160	mW/ch
Isolation Voltage ²		BV	5 000		Vr.m.s.
Operating Ambient Temperature		T _A	-55 to +100		°C
Storage Temperature		T _{stg}	-55 to +150		°C

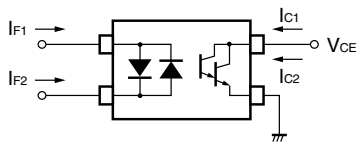
*1 PW = 100 μs, Duty Cycle = 1%

*2 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output
 Pins 1-2 shorted together, 3-4 shorted together (PS2506-1, PS2506L-1).
 Pins 1-4 shorted together, 5-8 shorted together (PS2506-2, PS2506L-2).
 Pins 1-8 shorted together, 9-16 shorted together (PS2506-4, PS2506L-4).

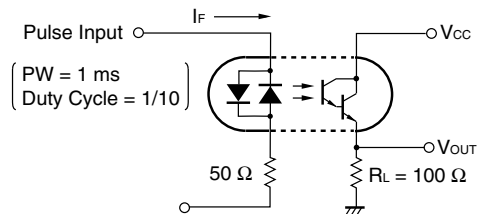
ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = ±10 mA		1.17	1.4	V
	Terminal Capacitance	C _t	V = 0 V, f = 1.0 MHz		100		pF
Transistor	Collector to Emitter Dark Current	I _{CEO}	V _{CE} = 40 V, I _F = 0 mA			400	nA
Coupled	Current Transfer Ratio (I _c /I _F)	CTR	I _F = ±1 mA, V _{CE} = 2 V	200	2 000		%
	CTR Ratio ^{*1}	CTR1/ CTR2	I _F = 1 mA, V _{CE} = 2 V	0.3	1.0	3.0	
	Collector Saturation Voltage	V _{CE(sat)}	I _F = ±1 mA, I _c = 2 mA			1.0	V
	Isolation Resistance	R _{i-o}	V _{i-o} = 1.0 kV _{DC}	10 ¹¹			Ω
	Isolation Capacitance	C _{i-o}	V = 0 V, f = 1.0 MHz		0.5		pF
	Rise Time ^{*2}	t _r	V _{CC} = 10 V, I _c = 2 mA, R _L = 100 Ω		100		μs
	Fall Time ^{*2}	t _f			100		

*1 CTR1 = I_{c1}/I_{F1}, CTR2 = I_{c2}/I_{F2}

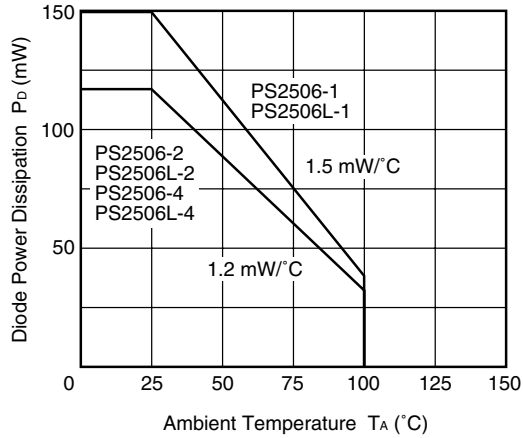


*2 Test circuit for switching time

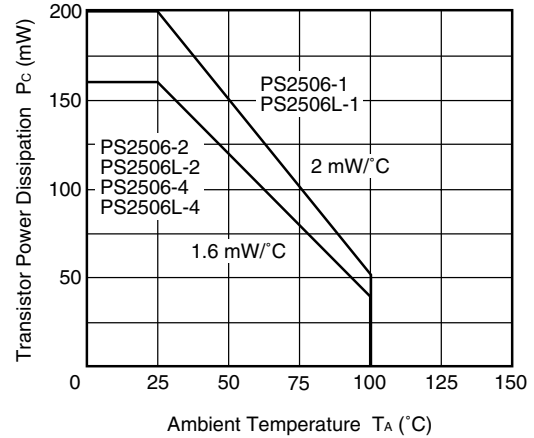


TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise specified)

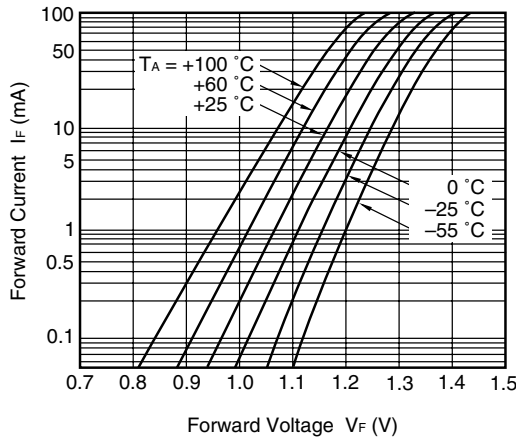
DIODE POWER DISSIPATION vs. AMBIENT TEMPERATURE



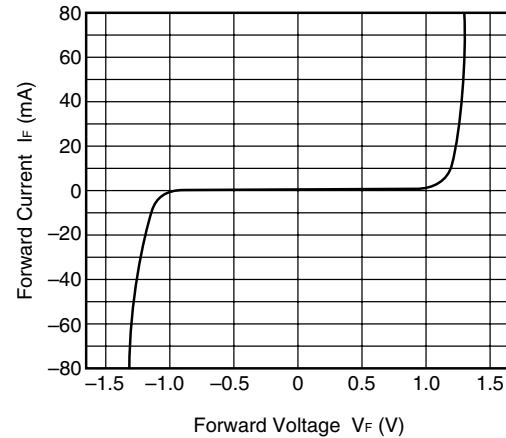
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



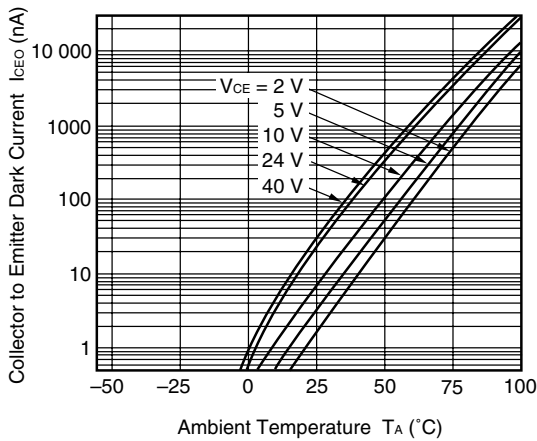
FORWARD CURRENT vs. FORWARD VOLTAGE



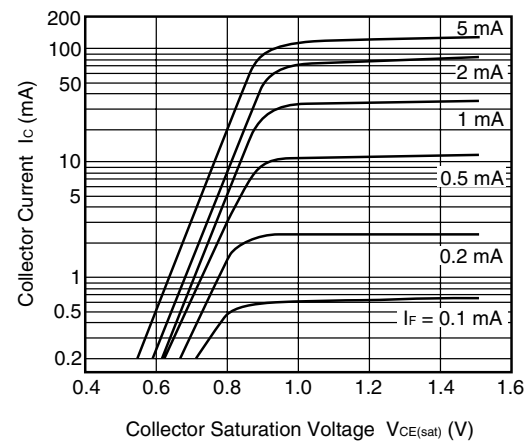
FORWARD CURRENT vs. FORWARD VOLTAGE



COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE

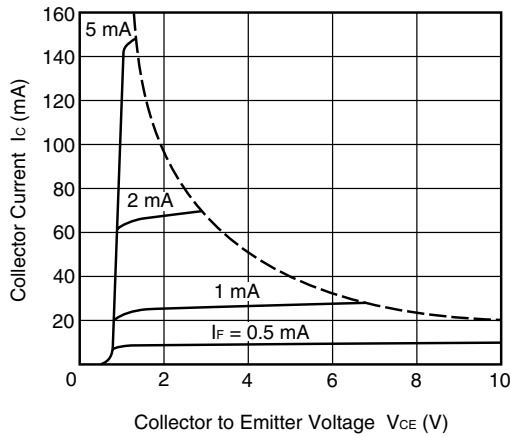


COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE

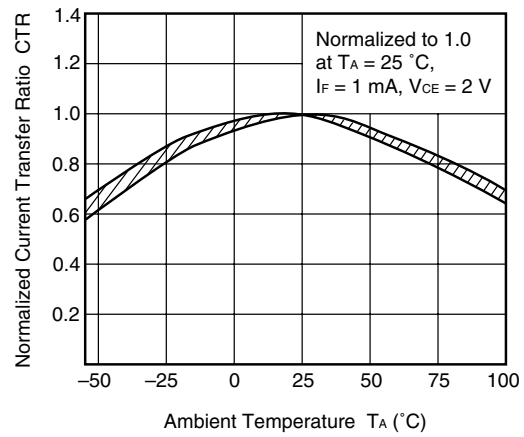


Remark The graphs indicate nominal characteristics.

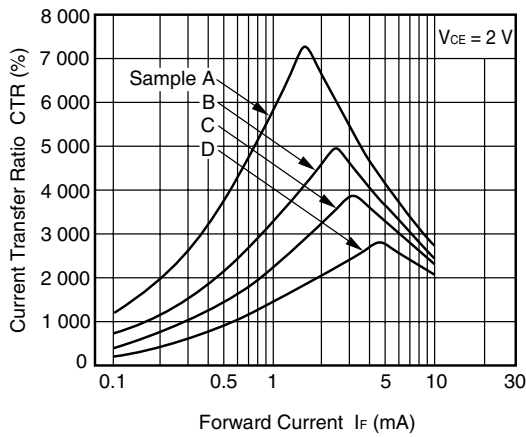
COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE



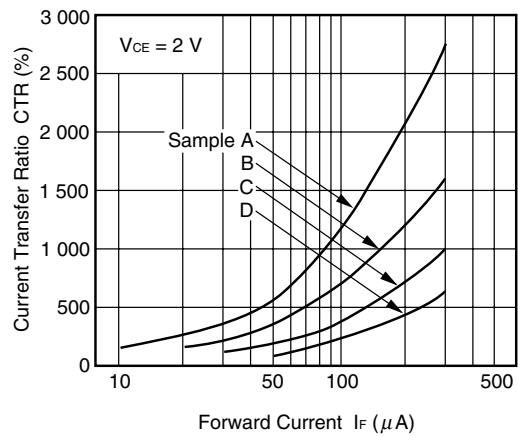
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



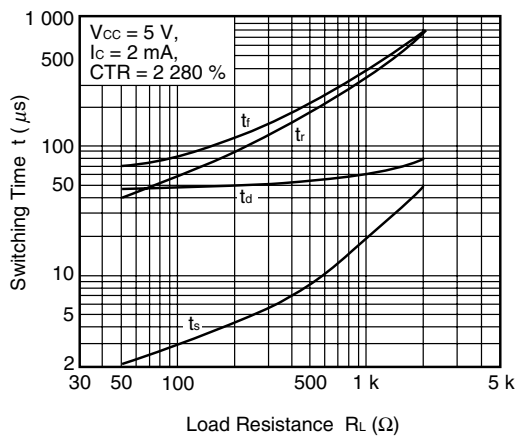
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



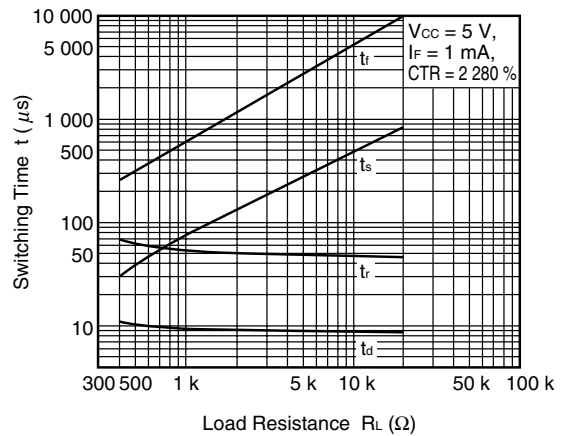
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



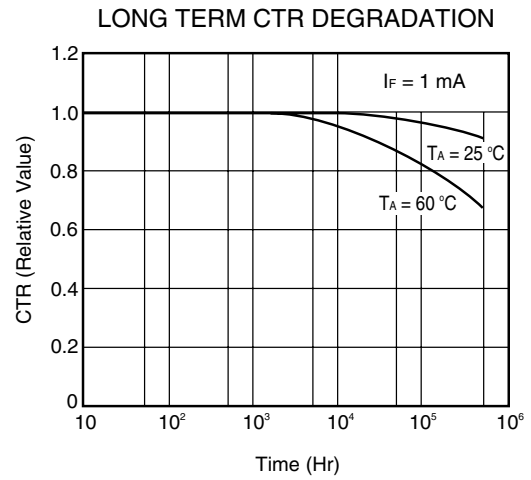
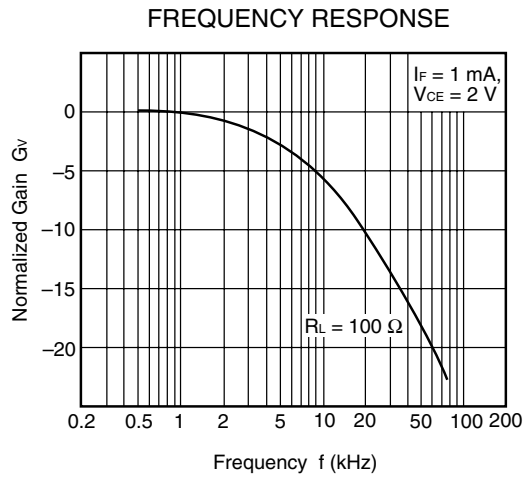
SWITCHING TIME vs. LOAD RESISTANCE



SWITCHING TIME vs. LOAD RESISTANCE



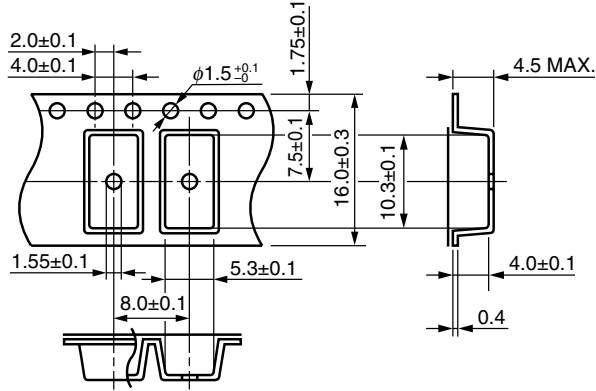
Remark The graphs indicate nominal characteristics.



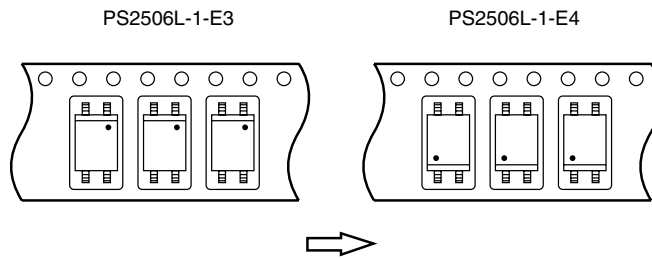
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT : mm)

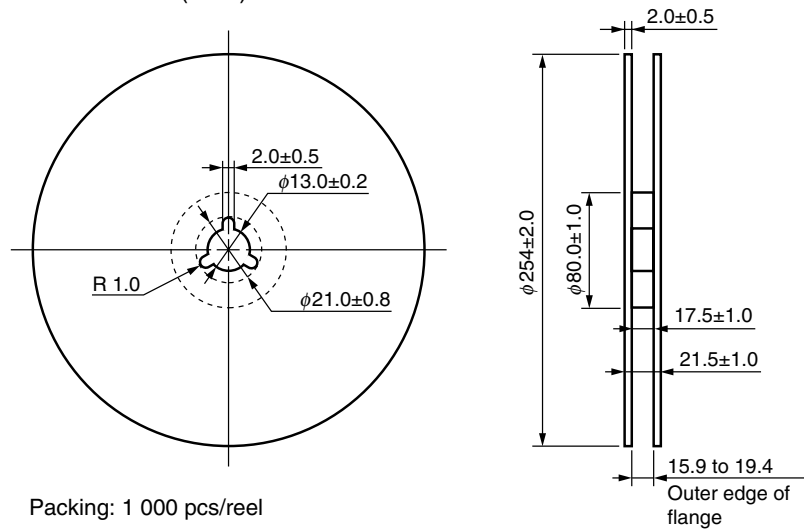
Outline and Dimensions (Tape)



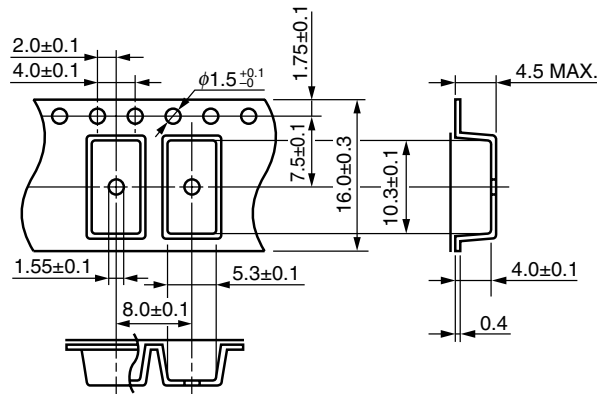
Tape Direction



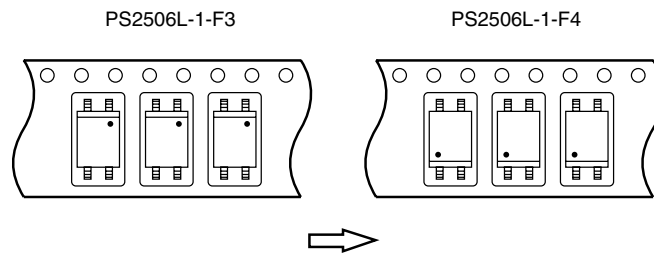
Outline and Dimensions (Reel)



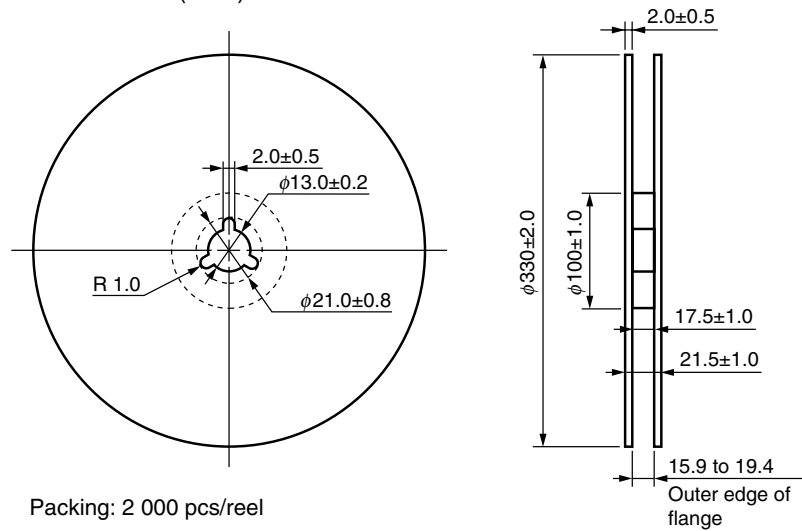
Outline and Dimensions (Tape)



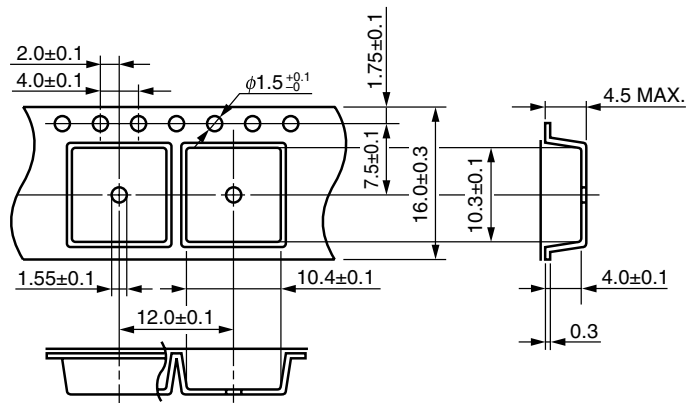
Tape Direction



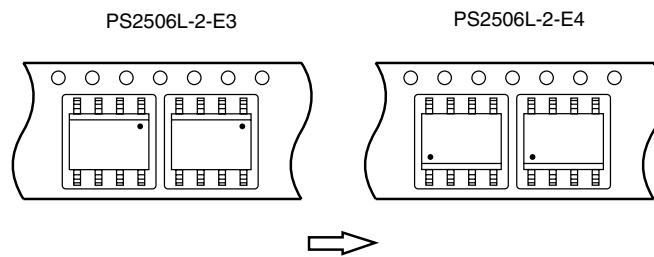
Outline and Dimensions (Reel)



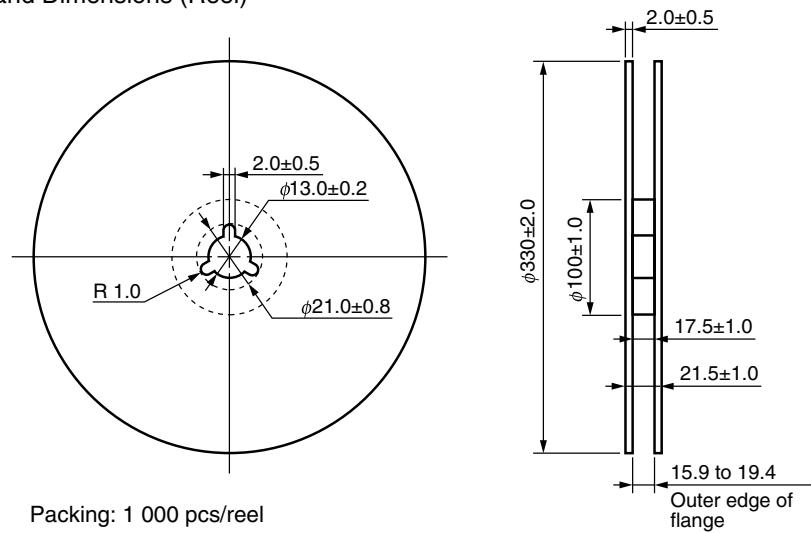
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



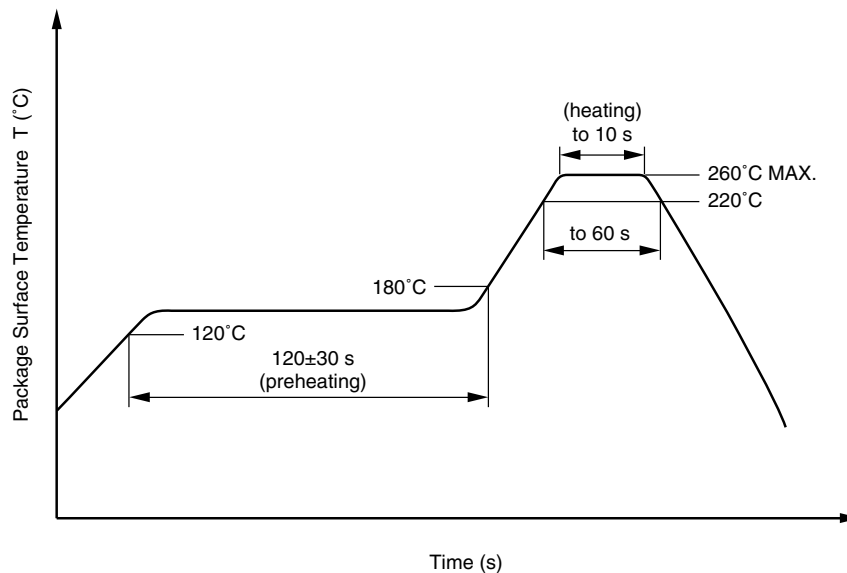
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

★ (3) Soldering by soldering iron

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

★ 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

When the product(s) listed in this document is subject to any applicable import or export control laws and regulation of the authority having competent jurisdiction, such product(s) shall not be imported or exported without obtaining the import or export license.

• **The information in this document is current as of March, 2006. The information is subject to change without notice. For actual design-in, refer to the latest publications of NEC's data sheets or data books, etc., for the most up-to-date specifications of NEC semiconductor products. Not all products and/or types are available in every country. Please check with an NEC sales representative for availability and additional information.**

• No part of this document may be copied or reproduced in any form or by any means without prior written consent of NEC. NEC assumes no responsibility for any errors that may appear in this document.

• NEC does not assume any liability for infringement of patents, copyrights or other intellectual property rights of third parties by or arising from the use of NEC semiconductor products listed in this document or any other liability arising from the use of such products. No license, express, implied or otherwise, is granted under any patents, copyrights or other intellectual property rights of NEC or others.

• Descriptions of circuits, software and other related information in this document are provided for illustrative purposes in semiconductor product operation and application examples. The incorporation of these circuits, software and information in the design of customer's equipment shall be done under the full responsibility of customer. NEC assumes no responsibility for any losses incurred by customers or third parties arising from the use of these circuits, software and information.

• While NEC endeavours to enhance the quality, reliability and safety of NEC semiconductor products, customers agree and acknowledge that the possibility of defects thereof cannot be eliminated entirely. To minimize risks of damage to property or injury (including death) to persons arising from defects in NEC semiconductor products, customers must incorporate sufficient safety measures in their design, such as redundancy, fire-containment, and anti-failure features.

• NEC semiconductor products are classified into the following three quality grades:

"Standard", "Special" and "Specific". The "Specific" quality grade applies only to semiconductor products developed based on a customer-designated "quality assurance program" for a specific application. The recommended applications of a semiconductor product depend on its quality grade, as indicated below. Customers must check the quality grade of each semiconductor product before using it in a particular application.

"Standard": Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots

"Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)

"Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

The quality grade of NEC semiconductor products is "Standard" unless otherwise expressly specified in NEC's data sheets or data books, etc. If customers wish to use NEC semiconductor products in applications not intended by NEC, they must contact an NEC sales representative in advance to determine NEC's willingness to support a given application.

(Note)

(1) "NEC" as used in this statement means NEC Corporation, NEC Compound Semiconductor Devices, Ltd. and also includes its majority-owned subsidiaries.

(2) "NEC semiconductor products" means any semiconductor product developed or manufactured by or for NEC (as defined above).

M8E 00.4-0110

Caution	GaAs Products	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. <ol style="list-style-type: none"> 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
----------------	---------------	---

► For further information, please contact

NEC Compound Semiconductor Devices, Ltd. <http://www.ncsd.necel.com/>

E-mail: salesinfo@ml.ncsd.necel.com (sales and general)
 techinfo@ml.ncsd.necel.com (technical)

Sales Division TEL: +81-44-435-1573 FAX: +81-44-435-1579

NEC Compound Semiconductor Devices Hong Kong Limited

E-mail: ncsd-hk@elhk.nec.com.hk (sales, technical and general)

Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309

Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859

Korea Branch Office TEL: +82-2-558-2120 FAX: +82-2-558-5209

NEC Electronics (Europe) GmbH <http://www.ee.nec.de/>

TEL: +49-211-6503-0 FAX: +49-211-6503-1327

California Eastern Laboratories, Inc. <http://www.cel.com/>

TEL: +1-408-988-3500 FAX: +1-408-988-0279